

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Shu-Wei Vanessa Chung</td> <td>10/05/2009</td> </tr> <tr> <td>Kuo-Feng Yu</td> <td>10/05/2009</td> </tr> </tbody> </table>		Name	Execution Date	Shu-Wei Vanessa Chung	10/05/2009	Kuo-Feng Yu	10/05/2009						
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CORRESPONDENCE DATA													
<p>Fax Number: 2142000853 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: 214-651-5000 Email: ipdocketing@haynesboone.com Correspondent Name: Haynes and Boone, LLP. Address Line 1: 2323 Victory Avenue Address Line 2: Suite 700 Address Line 4: Dallas, TEXAS 75219</p>													
ATTORNEY DOCKET NUMBER:	2008-0141-C / 24061.2408												
NAME OF SUBMITTER:	Kyle Howard												
<p>Total Attachments: 2 source=24061-2408_Assignment#page1.tif source=24061-2408_Assignment#page2.tif</p>													

OP \$40.00 13735831

ASSIGNMENT

WHEREAS, we,

- (1) Shu-Wei Vanessa Chung of 3F-3, No. 255, Sec. 2, Situng Road
Situng District, Taichung, Taiwan, R.O.C.
- (2) Kuo-Feng Yu of 11F, 41, Shih Pin Road
Hsin-Chu 300-77, Taiwan, R.O.C.

have invented certain improvements in

HIGH VOLTAGE DEVICE WITH REDUCED LEAKAGE

for which we have executed an application for Letters Patent of the United States of America on August 28, 2009, as U.S. Serial No. 12/549,540; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

Docket No.: 2008-0141 / 24061.1110
Customer No.: 42717

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Shu-Wei Vanessa Chung

Residence Address: 3F-3, No. 255, Sec. 2, Situng Road
Situng District, Taichung, Taiwan, R.O.C.

Dated: 2009.10.5

Shu-Wei Chung 鍾淑偉
Inventor Signature

Inventor Name: Kuo-Feng Yu

Residence Address: 11F, 41, Shih Pin Road
Hsin-Chu 300-77, Taiwan, R.O.C.

Dated: 2009.10.5

Kuo-Feng Yu
Inventor Signature